V_{DSS}	30	V
I_D	26	A
$R_{DS(ON)}$	10	mΩ

Features

Excellent gate charge x $R_{DS(on)}$ product(FOM)

$R_{DS(on).typ}$=10mΩ@V_{GS}=10V

High Reliability Capability

Application

Charger

DC/DC Converter

Ideal for high-frequency switching

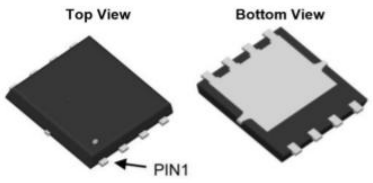
GK xxx
T010N03

LOGO GK xxx CODE

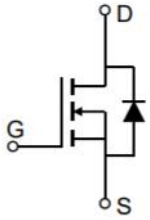
T010N03

RDS(ON) VDSS

PDFN3X3- top&bottomview



Equivalent Circuit



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (T_C=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-source Voltage	V_{DS}	30	V
Continuous Drain Current T_C = 25°C T_C = 100°C	I_D	 26 22	A
Pulsed Drain Current	$I_{D\ pulse}$	104	A
Avalanche Energy, Single Pulse	E_{AS}	49	mJ
Gate-emitter Voltage	V_{GS}	±20	V
Power Dissipation, T_C = 25℃	P_D	31	W
Operating Junction And Storage Temperature	T_j , T_{stg}	-55~150	℃

Thermal Resistance

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance, Junction to Case	R_{thJC}	-	4	℃/W
Thermal Resistance, Junction to Ambient	R_{thJA}	-	52	℃/W

Electrical Characteristics (T_J=25℃unless otherwise noted)

Parameter	Symbol	Test Condition	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Drain-source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D=250uA	30	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250uA	1	1.5	2.4	
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=30V, V_{GS}=0V	-	-	1	μA
Gate-source leakage current	I_{GSS}	V_{GS}=±20V, V_{DS}=0V	-	-	±100	nA
Drain-source on-state Resistance	$R_{DS(on)}$	V_{GS}=10V, I_D=20A	-	10	12	mΩ
Dynamic Characteristic						
Input Capacitance	C_{iss}	V_{GS}=0V,	-	810	-	pF
Output Capacitance	C_{oss}	V_{DS}=15V,	-	111	-	
Reverse Transfer Capacitance	C_{rss}	f=1MHz	-	84	-	
Gate Total Charge	Q_g	V_{GS}=10V,	-	6	-	nC
Gate-Source charge	Q_{gs}	V_{DS}=15V,	-	1	-	
Gate-Drain charge	Q_{gd}	I_D=10A	-	2	-	
Turn-on Delay Time	$t_{d(on)}$	V_{GS}=10V,	-	10	-	ns
Turn-on Rise Time	t_r	V_{DD}=15V,	-	12	-	
Turn-off Delay Time	$t_{d(off)}$	I_D=10A,	-	9	-	
Turn-off Fall Time	t_f	R_G=3Ω	-	6	-	
Body Diode Characteristic						
Body Diode Forward Voltage	V_{SD}	V_{GS}=0V,I_{SD}=10A	-	-	1.2	V
Reverse Recovery Time	t_{rr}	I_F=10A,	-	20	-	ns
Reverse Recovery Charge	Q_{rr}	dI_F/dt=100A/us	-	28	-	nC

RATING AND CHARACTERISTIC CURVES

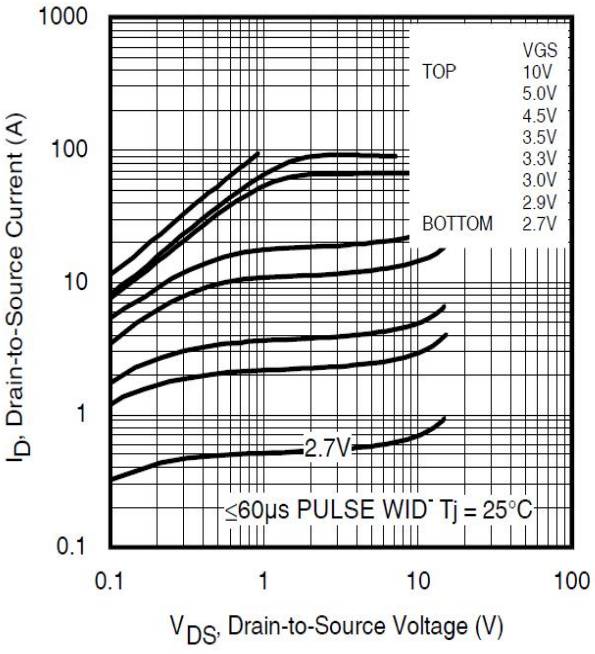


Fig 1. Typical Output Characteristics

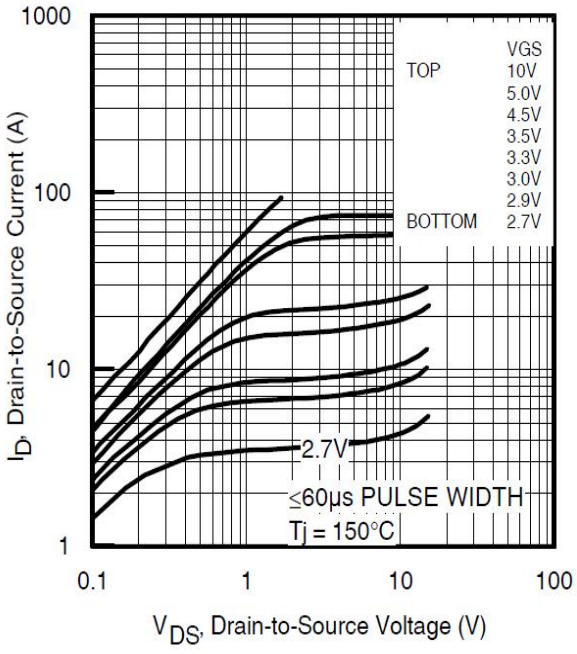


Fig 2. Typical Output Characteristics

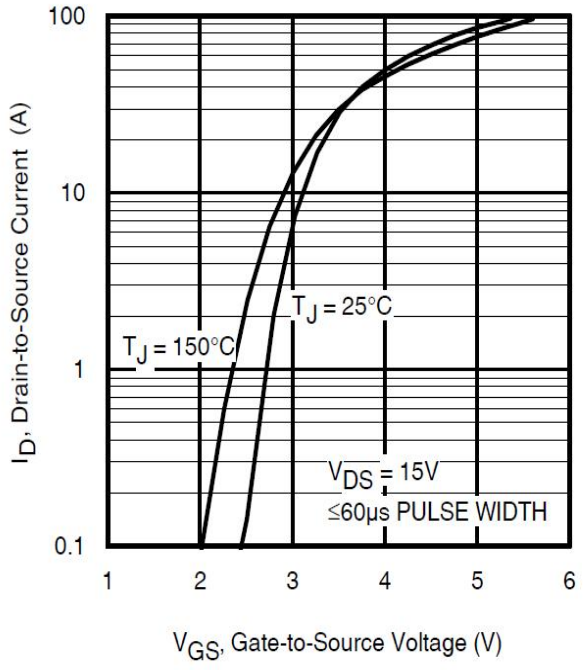


Fig 3. Typical Transfer Characteristics

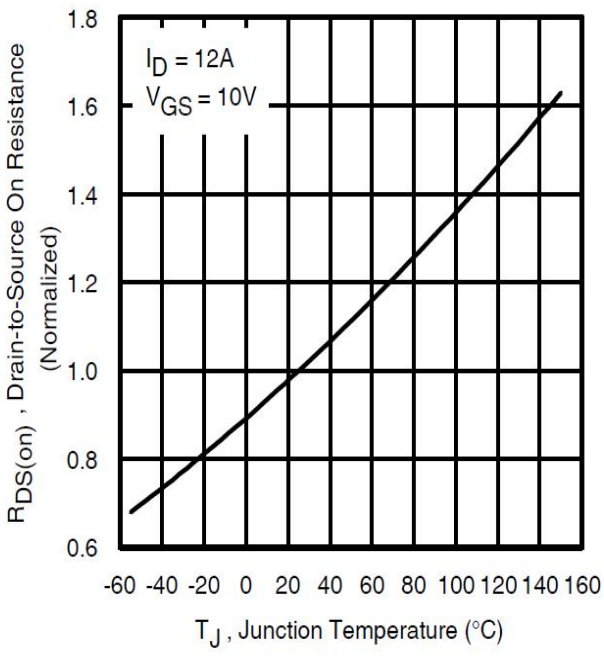


Fig 4. Normalized On-Resistance Vs. Temperature

RATING AND CHARACTERISTIC CURVES

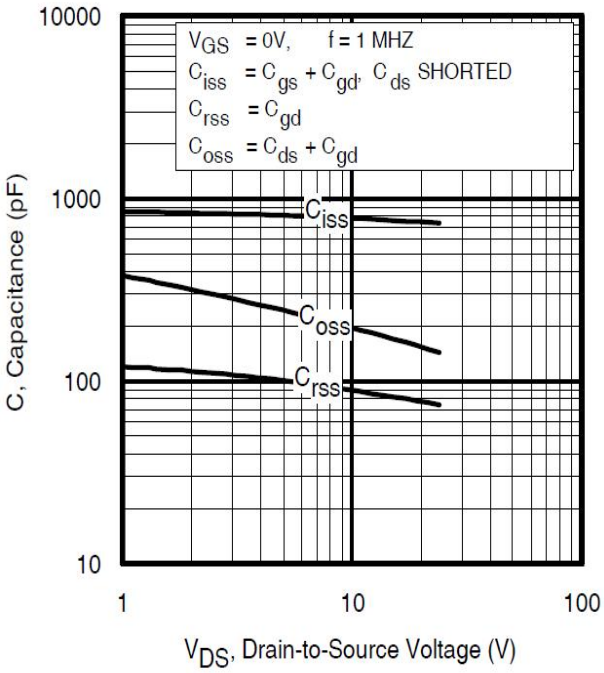


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

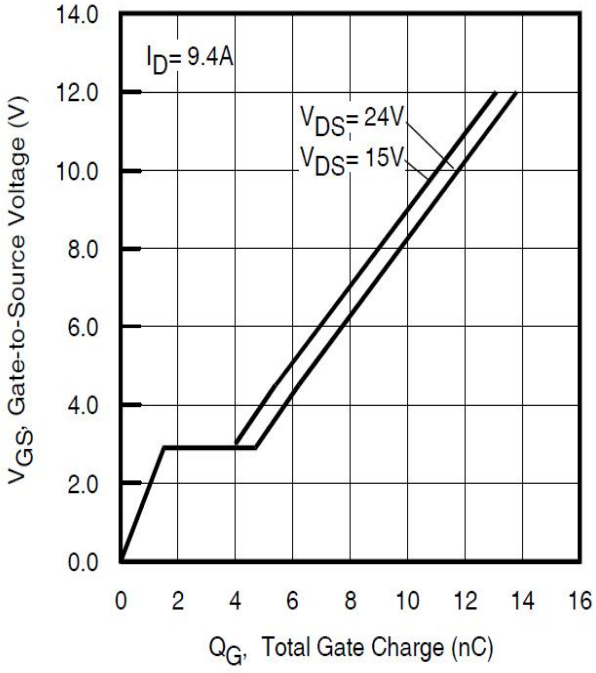


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

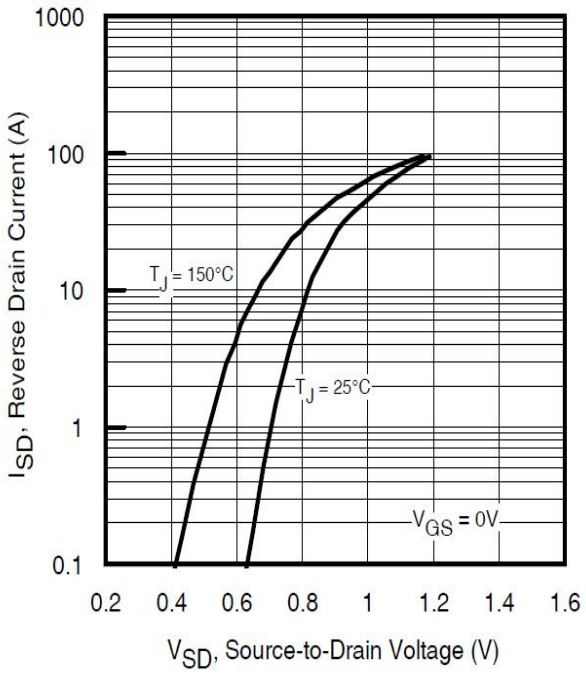


Fig 7. Typical Source-Drain Diode Forward Voltage

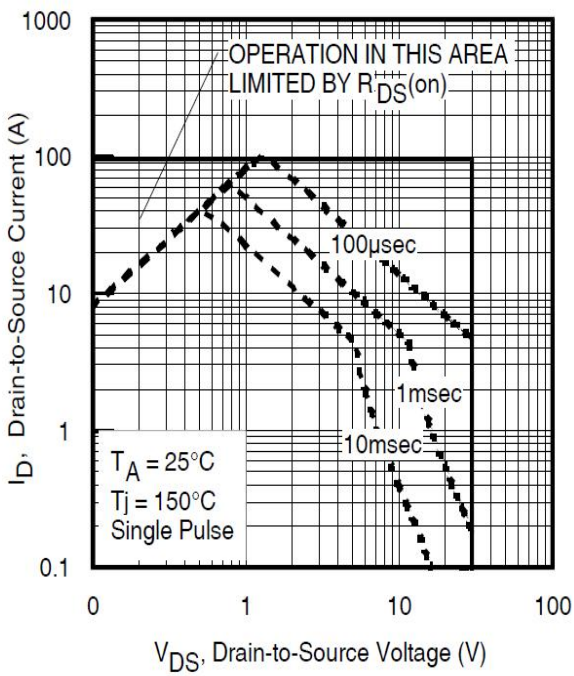


Fig 8. Maximum Safe Operating Area

RATING AND CHARACTERISTIC CURVES

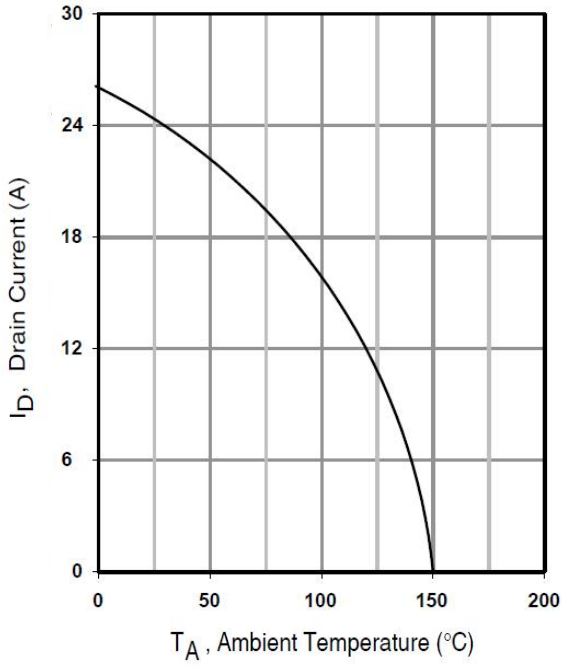


Fig 9. Maximum Drain Current Vs. Ambient Temperature

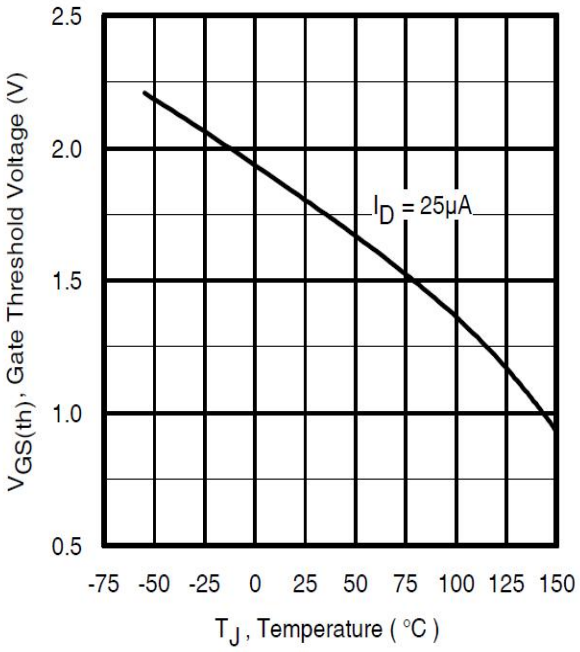


Fig 10. Threshold Voltage Vs. Temperature

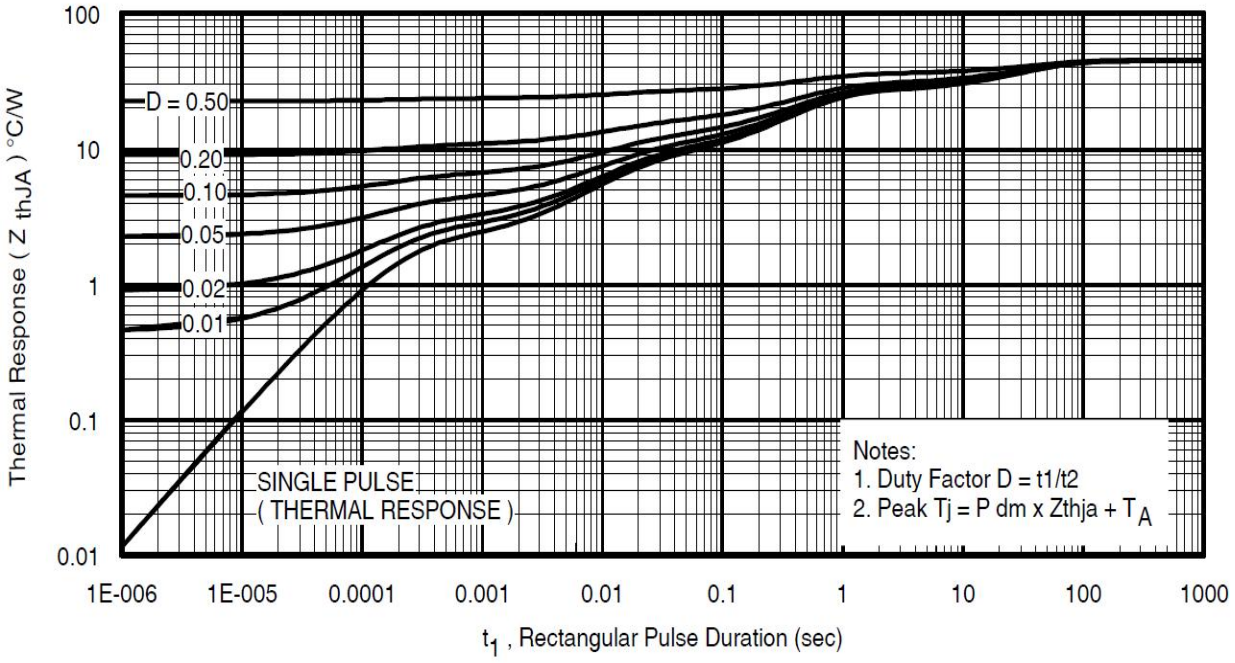


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

RATING AND CHARACTERISTIC CURVES

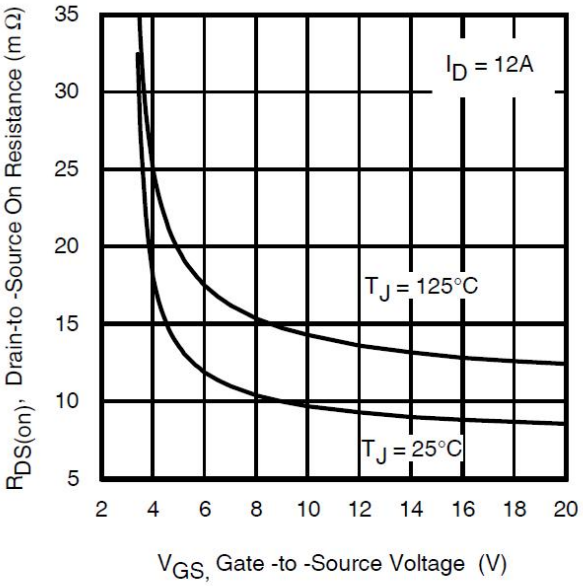


Fig 12. On-Resistance vs. Gate Voltage

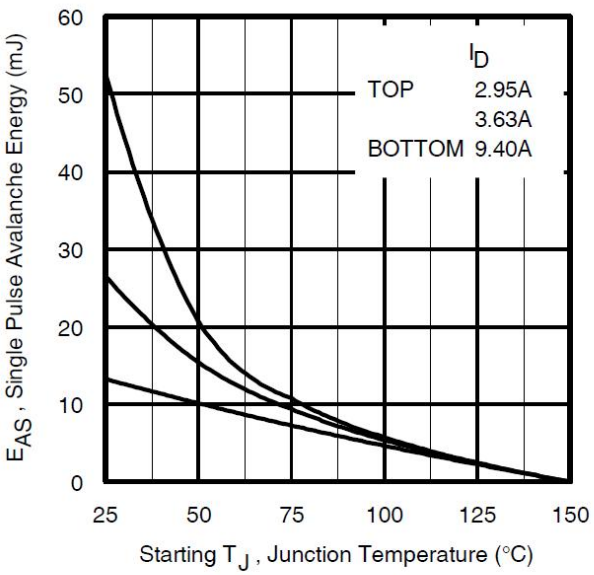
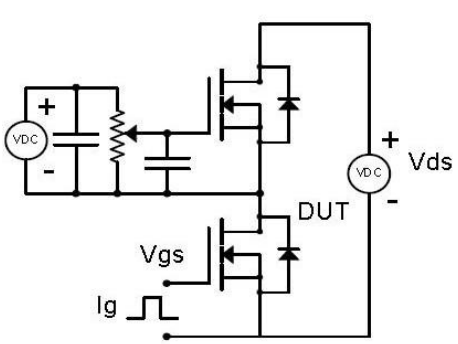
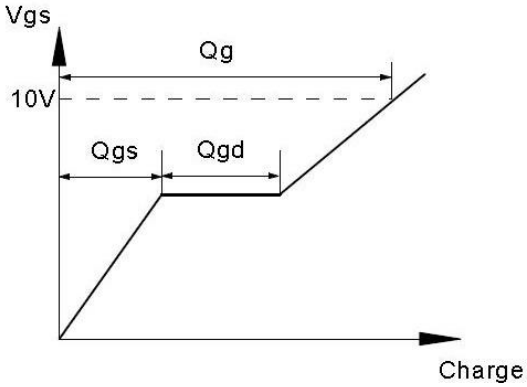


Fig 13. Maximum Avalanche Energy vs. Drain Current

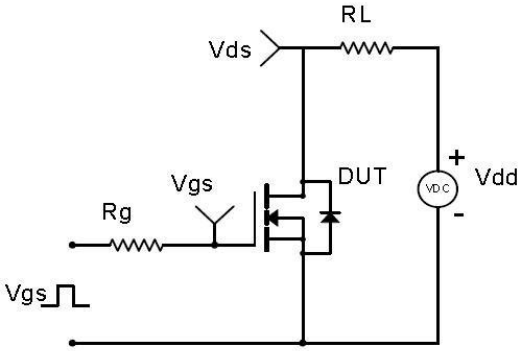
Test Circuit & Waveform

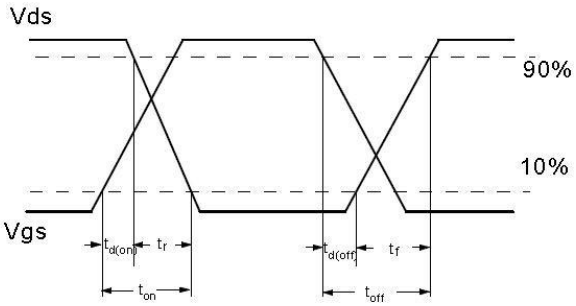
Gate Charge Test Circuit & Waveform



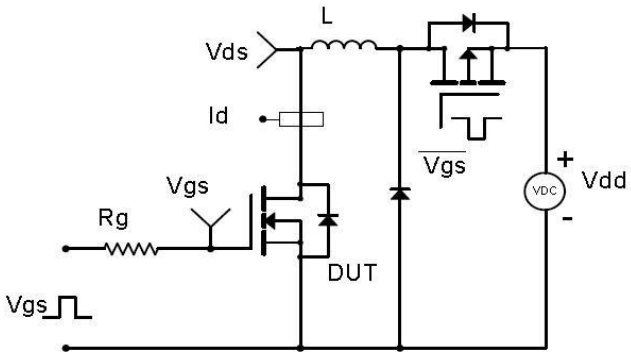


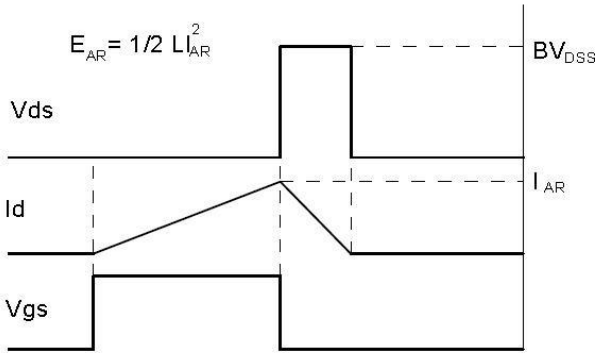
Resistive Switching Test Circuit & Waveforms



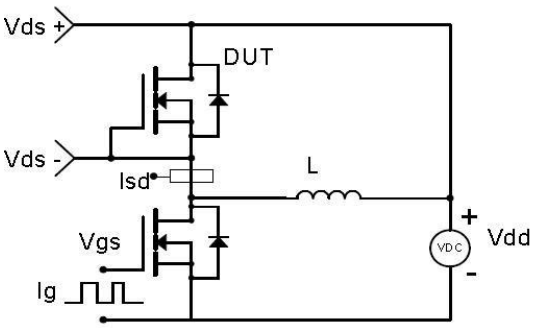


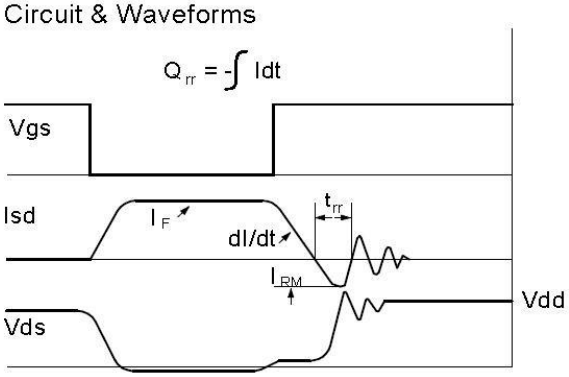
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





Diode Recovery Test Circuit & Waveforms

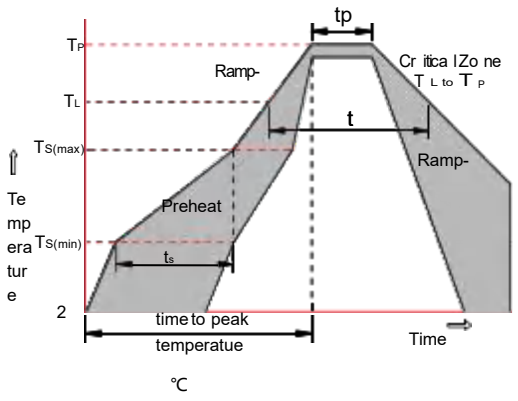




Soldering parameters

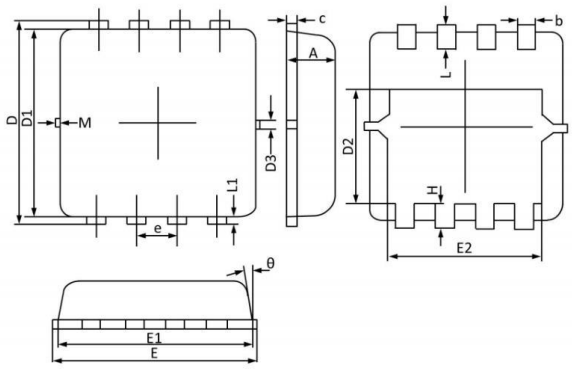
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

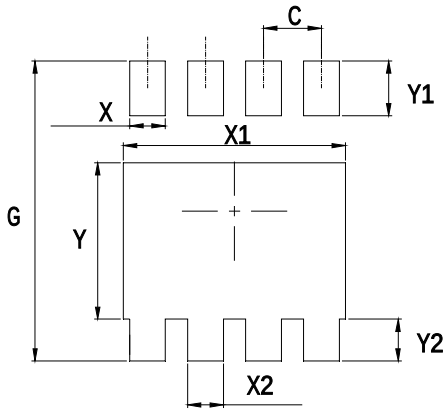
FIG5: Reflow condition



Package Dimensions & Suggested Pad Layout

PDFN3X3 Package Information





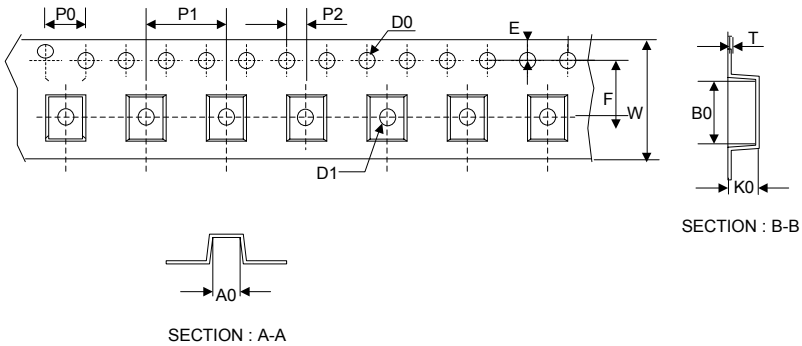
DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.70	0.75	0.80	b	0.25	0.30	0.35
C	0.10	0.15	0.25	D	3.25	3.35	3.45
D1	3.00	3.10	3.20	D2	1.78	1.88	1.98
D3	--	0.13	--	E	3.20	3.30	3.40
E1	3.00	3.15	3.20	E2	2.39	2.49	2.59
e	0.65BSC			H	0.30	0.39	0.50
L	0.30	0.40	0.50	L1	--	0.13	--
θ	--	10°	12°	M	*	*	0.15

Dimensions	Value (in mm)
C	0.65
G	3.60
X	0.40
X1	2.60
X2	0.40
Y	1.95
Y1	0.62
Y2	0.55

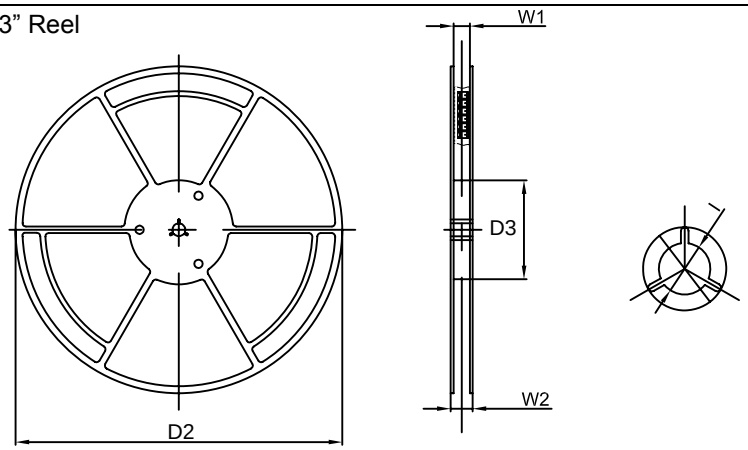
Tape & rell specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.20
P1	8.00±0.20
P2	2.00±0.20
D0	1.55±0.20
D1	1.55±0.20
E	1.75±0.20
F	5.50±0.20
W	12.00±0.20
A0	3.90±0.20
B0	3.80±0.20
K0	1.20±0.20
T	0.20±0.20

13” Reel



D2	330.0±5.0
D3	100.0±4.0
W1	12.0±5.0
W2	14.0±5.0
I	13.0±2.0

Quantity: 5000PCS